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		Application No.: 09/997,378	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>		First Named Inventor: Ligang Zhang	
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		Group Art Unit: 2832	
		Examiner Name: Tuyen T. Nguyen	
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<b>NON PATENT LITERATURE DOCUMENTS</b>			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of author (in CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
TN	AA	FROMMBERGER, Michael, et al., "Integration of Crossed Anisotropy Magnetic Core Into Toroidal Thin-Film Inductors," IEEE Transactions on Microwave Theory and Techniques, Vol. 53, No. 6, June 2005, pp. 2096-2100. No Date	
TN	AB	KIM, Sung-Jin, et al., "Realization of High-Q Inductors Using Wirebonding Technology," School of Electronics Engineering, Ajou University, AP-ASIG Proceedings, August 1999, 4 pages. No Date	
TN	AC	LONG, John R. and Miles A. Copeland, "The Modeling, Characterization, and Design of Monolithic Inductors for Silicon RF IC's," IEEE Journal of Solid-State Circuits, Vol. 32, No. 3, March 1997, pp. 357-369. No Date	
TN	AD	SOH, H. T., et al., "Through-Wafer Vias (TWV) and their Applications in 3 Dimensional Structures," Proceedings of 1998 International Conference on Solid State Devices and Materials, September 1998, 12 pages. No Date	
TN	AE	TANG, Chih-Chun, et al., "Miniature 3-D Inductors in Standard CMOS Process," IEEE Journal of Solid-State Circuits, Vol. 37, No. 4, April 2002, pp. 471-480. No Date	
	AF	TRELEAVEN, Dave and Dick James, "Integrated Circuit Passive Components," Whitepapers, Chipworks, <a href="http://www.chipworks.com/resources/resources_whitepapers.asp">www.chipworks.com/resources/resources_whitepapers.asp</a> , 4 pages.	
TN	AG	TSUI, Hau-Yiu and Jack Lau, 2003 IEEE MTT-S Digest, pp. 225-228. No Month	
TN	AH	WU, Joyce H., et al., "A Through-Wafer Interconnect in Silicon for RFICs," IEEE Transactions on Electron Devices, Vol. 51, No. 11, November 2004, pp. 1765-1771. No Date	
TN	AI	ZANNOTH, Markus, et al., "A Fully Integrated VCO at 2 GHz," IEEE Journal of Solid-State Circuits, Vol. 33, No. 12, December 1998, pp. 1987-1991. No Date	
TN	AJ	ZOU, Jun, et al., "Development of Vertical Planar Coil Inductors Using Plastic Deformation Magnetic Assembly (PDMA), 2001 IEEE International Microwave Symposium, May 2001, 4 pages. No Date	
Examiner Signature		/Tuyen Nguyen/	Date Considered 10/30/2006

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Applicant's unique citation designation number (optional).

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